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EC74

**Seventh Semester B.E. Degree Examination, June 2012**  
**VLSI Circuits**

Time: 3 hrs.

Max. Marks:100

**Note: 1. Answer any FIVE full questions.****2. Assume typical device parameter values, if necessary.**

- 1 a. Using the flowchart, explain the "Top down" and "Bottom up" approach in VLSI design. (05 Marks)
- b. Explain the complexity of VLSI chip using the idea of VLSI design funnel. (05 Marks)
- c. Explain the concept of bubble pushing to build the PFET array of MOSFET circuit. Using this technique construct the CMOS logic gate for the function  $g = x \cdot (y + z) + y$ . Use minimum transistors in the design. (10 Marks)
- 2 a. Discuss the pass characteristics of nFETs. Show that nFETs pass strong logic zero voltages but weak logic 1 values. (06 Marks)
- b. Consider the three MOSFETs connected as shown in Fig.Q2(b). Find  $V_{out}$  for the following values of  $V_a$ ,  $V_b$  and  $V_c$ . Assume  $V_{DD} = 3.3V$ ,  $V_{Th} = 0.6V$ .

i)  $V_a = 3.3V$ ,  $V_b = 3.3V$ ,  $V_c = 3.3V$

ii)  $V_a = 3V$ ,  $V_b = 0.5V$ ,  $V_c = 3V$

iii)  $V_a = 3.3V$ ,  $V_b = 1.8V$ ,  $V_c = 1.5V$

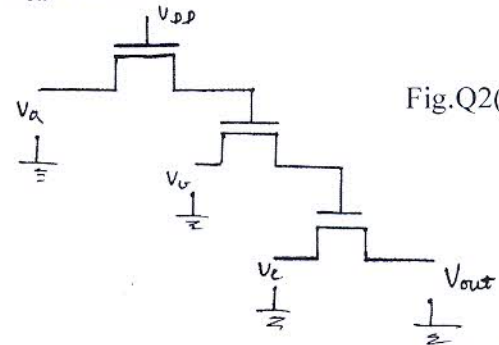
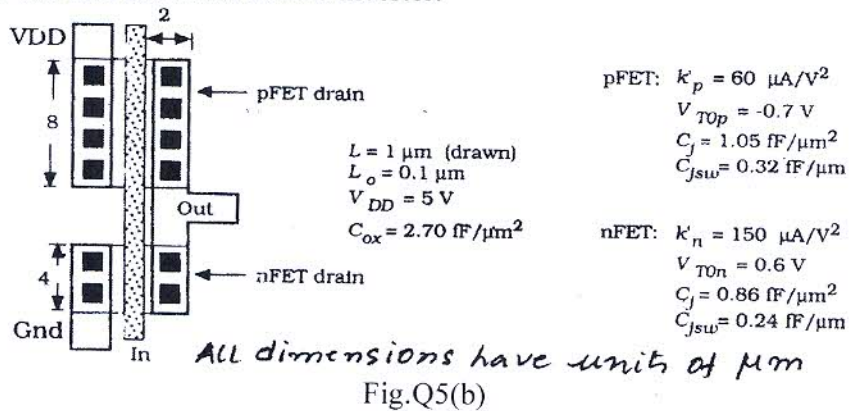


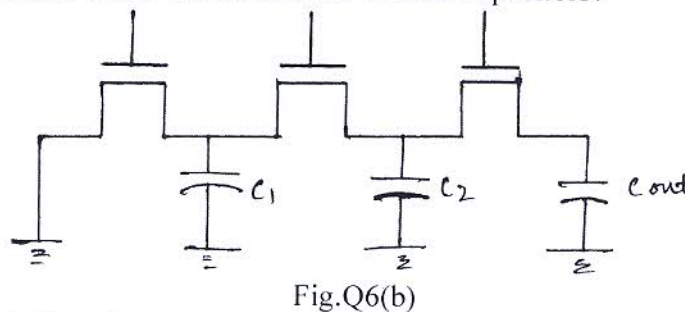
Fig.Q2(b)

- c. Design 4:1 multiplexer using transmission gate switches. (08 Marks)
- 3 a. With the cross-sectional schematic view of a N well CMOS process. Identify various layers. (04 Marks)
- b. A sample of silicon is doped with boron atoms at an acceptor density of  $N_a = 4 \times 10^{14} \text{ cm}^{-3}$ 
  - i) Find majority and minority carrier densities.
  - ii) Find the resistivity  $\rho$  of the sample.
  - iii) Suppose the region has dimensions of  $W = 2\mu\text{m}$ ,  $t = 0.5\mu\text{m}$  and  $L = 100\mu\text{m}$ . Find resistance of end to end block of the region. (06 Marks)
- c. Design the circuit and layout for a CMOS gate that implements the function,  $F = a \cdot bc + a \cdot d$ , using fewest number of transistors. (10 Marks)
- 4 a. Explain the latch up prevention in a bulk CMOS technology. (08 Marks)
- b. With cross-sectional view illustrate the use of a via to connect metall to metal2. Draw the layout including design rule. (06 Marks)
- c. Implement symmetric inverter with vertical FETs. Explain with neat layout. (06 Marks)

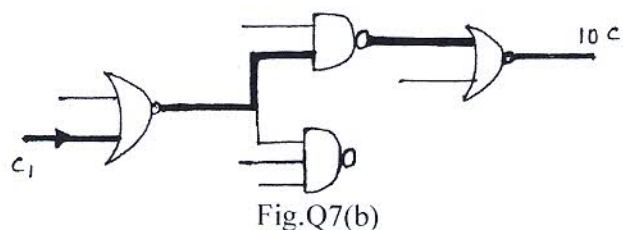
- 5 a. Derive expression for rise time and fall time for a CMOS inverter circuit. (08 Marks)  
 b. Consider the NOT gate shown in Fig.Q5(b). When an external load of  $C_L = 80$  fF is connected to output, find i) the input capacitance of the circuit ii) Values of  $R_n$  and  $R_p$  iii) Calculate rise and fall times for the inverter. (12 Marks)



- 6 a. Explain speed versus area trade off in chip design. (06 Marks)  
 b. Consider nFET chain as in Fig.Q6(b). The transistors are identical with  $\beta_n = 2.0$  mA/V<sup>2</sup> in a process where  $V_{DD} = 3.3$ V,  $V_{Tn} = 0.7$ V. The output capacitance has value of  $C_{out} = 130$ fF, while the internal values are  $C_1 = 36$  fF and  $C_2 = 36$  fF.  
 i) Find the discharge time constant using the Elmore formula for RC ladder network for  $C_{out} = 130$  fF.  
 ii) Find the time constant if we ignore  $C_1$  and  $C_2$ , what is the percentage error introduced if we do not include the internal capacitors? (06 Marks)



- c. Explain NOR2 switching times. (08 Marks)
- 7 a. Construct a BiCMOS NOR2 circuit. (08 Marks)  
 b. Define i) Logical effort ii) Electrical effort.  
 The long chain in Fig.Q7(b) is constructed in a process with  $r = 2.5$ . Determine the optimum sizing for each stage for the "highlighted" path indicated using the technique of logical effort. (12 Marks)



- 8 a. Explain the pseudo nMOS logic. (05 Marks)  
 b. Draw the circuit diagram for dynamic logic gate that has an output of  $f = a \cdot (b + c + d)$ . (05 Marks)  
 c. Compare blocked CMOS circuits with dynamic CMOS logic circuits, with neat diagrams and examples. (10 Marks)

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